

Technical Datasheet

takeMS TMS2GS264D08x-665xx

Description

These Memory devices are JEDEC standard unbuffered DIMM modules, based on CMOS DDR2 SDRAM technology.

These devices consist of CMOS DDR2 SDRAMs in FBGA packages on a 200-pin glass epoxy substrate. The memory array is designed with Double Data Rate (DDR2) Synchronous DRAMs for unbuffered applications.

The pipelined, multibanked architecture of DDR2 SDRAMs allows for concurrent operation, thereby providing high, effective bandwidth. Decoupling capacitors are mounted on the PCB board in parallel for each DDR2 SDRAM, which provides proper voltage supply impedance over the whole frequency range of operations, in accordance with JEDEC specifications.

These modules feature Serial Presence Detect (SPD) based on a serial EEPROM device, using the 2-pin I2C protocol.

Features	
200-pin Unbuffered SO-DIMM DDR2 SDRAM	
JEDEC standard 1.8V I/O (SSTL_18-compatible)	
Auto Refresh (CBR) and Self Refresh Mode	
Off-Chip Driver (OCD) Impedance Adjustment	
On-Die Termination (ODT) supports termination values of 50, 75, and 150 ohms	
Serial Presence Detect (SPD) with EEPROM	
Module layout is based on JEDEC standard routing guidelines	
Impedance controlled 6-layer PCB Technology	
JEDEC standard form factor	
DQS edge-aligned with data for READs	
DQS center-aligned with data for WRITEs	
Operating Temperature 0°C ~ 75°C	





Technical Datasheet

Technical details

- 2048 MB SO-DIMM module
- 128Mx8 IC organisation
- x64 module organisation
- 667 MHz / PC2 5300
- double sided / 16 ICs
- CAS Latency 5 at max. memclock

For pin configuration please check www.takems.com/support/index.php
If you have any questions regarding our products you can contact us via email: info@takems.com

Order-No.: TMS2GS264D08x-665xx



Fax: +49-7667-9414-444

